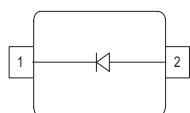
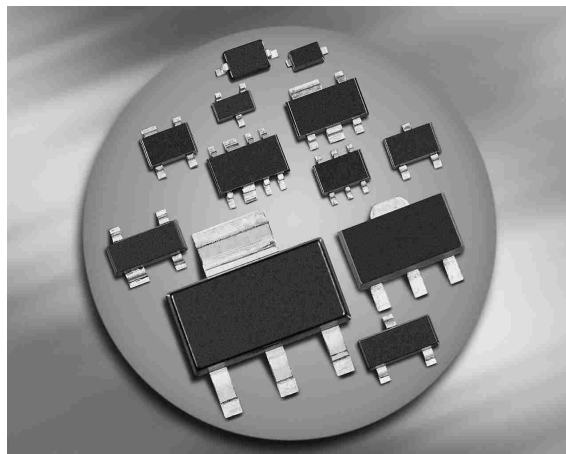


Silicon Tuning Diode

- For UHF-TV-tuners
- High capacitance ratio
- Low series inductance
- Low series resistance
- Excellent uniformity and matching due to "in-line" matching assembly procedure
- Pb-free (RoHS compliant) package



BB535
BB555/-02V



Type	Package	Configuration	L_S (nH)	Marking
BB535	SOD323	single	1.8	white S
BB555	SCD80	single	0.6	BB
BB555-02V	SC79	single	0.6	B

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	30	V
Peak reverse voltage $R \geq 5\text{k}\Omega$	V_{RM}	35	
Forward current	I_F	20	mA
Operating temperature range	T_{op}	-55 ... 150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 ... 150	

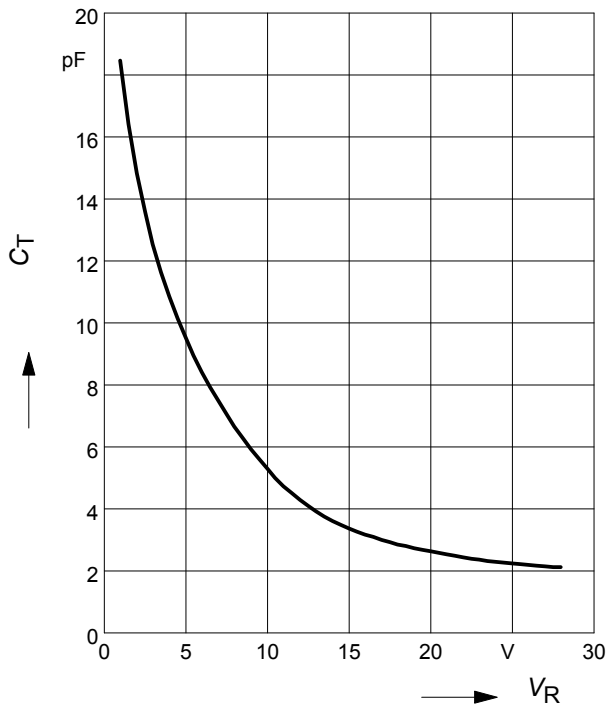
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Reverse current $V_R = 30\text{ V}$ $V_R = 30\text{ V}, T_A = 85\text{ }^{\circ}\text{C}$	I_R	- -	- -	10 200	nA
AC Characteristics					
Diode capacitance $V_R = 1\text{ V}, f = 1\text{ MHz}$ $V_R = 2\text{ V}, f = 1\text{ MHz}$ $V_R = 25\text{ V}, f = 1\text{ MHz}$ $V_R = 28\text{ V}, f = 1\text{ MHz}$	C_T	17.5 14.01 2.05 1.9	18.7 15 2.24 2.1	20 16.1 2.4 2.3	pF
Capacitance ratio $V_R = 1\text{ V}, V_R = 28\text{ V}, f = 1\text{ MHz}$	C_{T1}/C_{T28}	8.2	8.9	9.8	-
Capacitance ratio $V_R = 2\text{ V}, V_R = 25\text{ V}, f = 1\text{ MHz}$	C_{T2}/C_{T25}	6	6.7	7.5	
Capacitance matching ¹⁾ $V_R = 1\text{V to } 28\text{V}, f = 1\text{ MHz}, \mathbf{7}$ diodes sequence, BB535 $V_R = 1\text{V to } 28\text{V}, f = 1\text{ MHz}, \mathbf{4}$ diodes sequence, BB555/-02V $V_R = 1\text{V to } 28\text{V}, f = 1\text{ MHz}, \mathbf{7}$ diodes sequence, BB555/-02V	$\Delta C_T/C_T$	- - -	- 0.15 0.25	2.5 1 2	%
Series resistance $V_R = 3\text{ V}, f = 470\text{ MHz}$	r_S	-	0.58	0.75	Ω
Series inductance	L_S	-	0.6	-	nH

¹For details please refer to Application Note 047

Diode capacitance $C_T = f(V_R)$

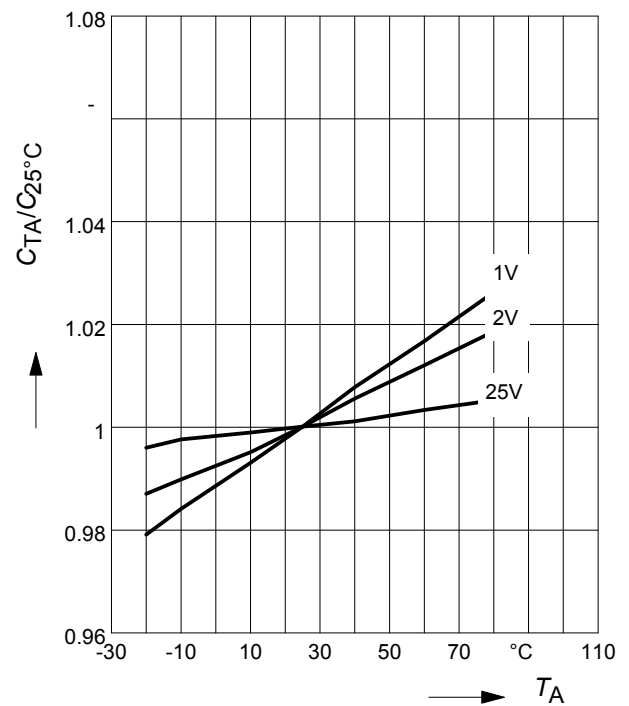
$f = 1\text{MHz}$



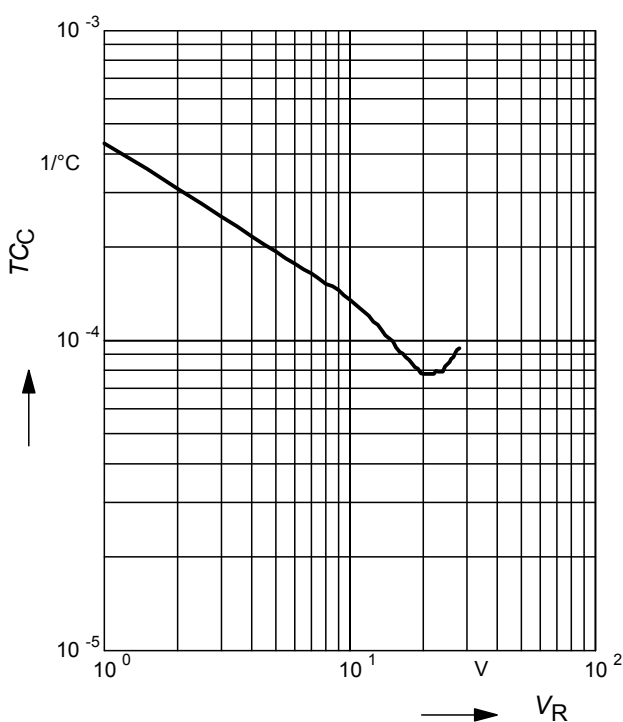
Normalized diode capacitance

$C_{(T_A)}/C_{(25^\circ\text{C})} = f(T_A); f = 1\text{MHz}$

$V_R = \text{Parameter}$

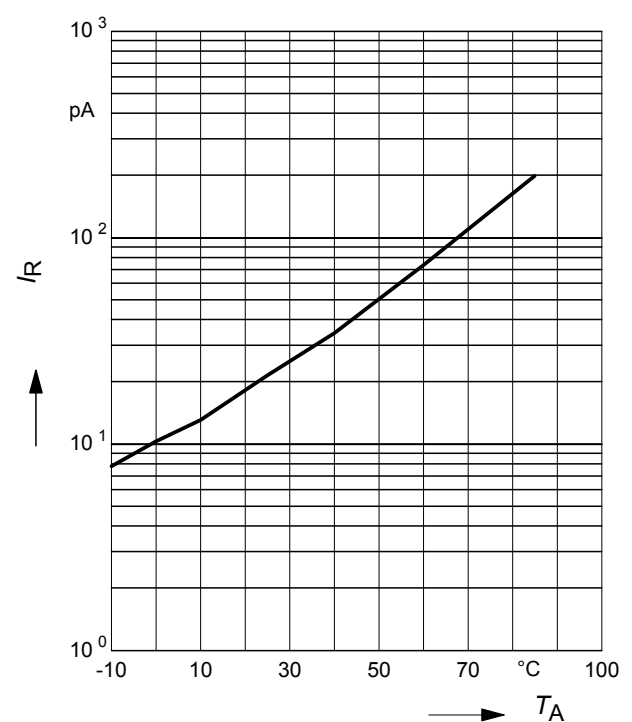


Temperature coefficient of the diode capacitance $T_{CC} = f(V_R)$



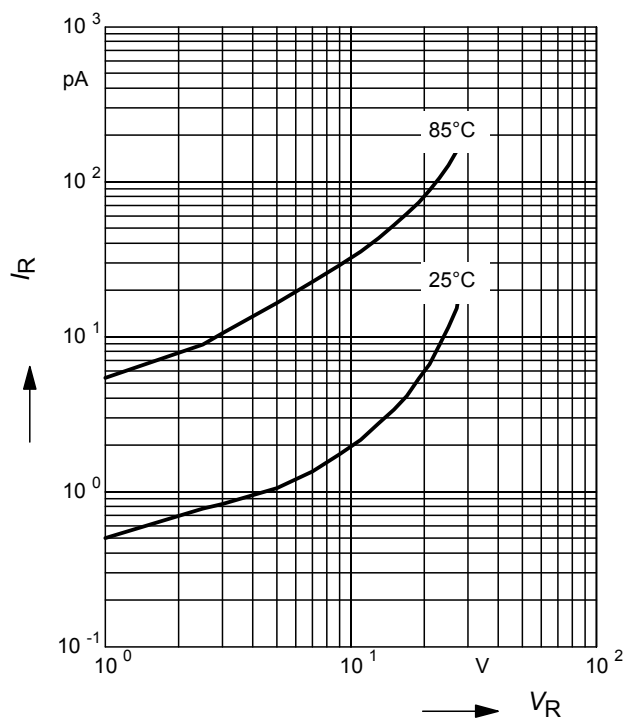
Reverse current $I_R = f(T_A)$

$V_R = 28\text{ V}$

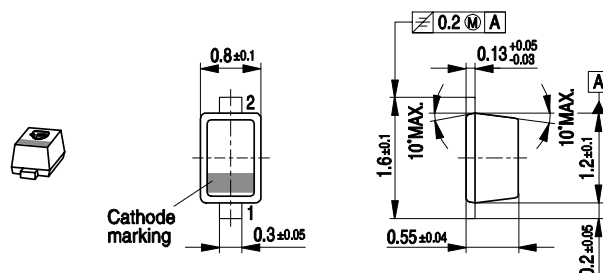


Reverse current $I_R = f(V_R)$

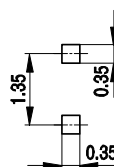
T_A = Parameter



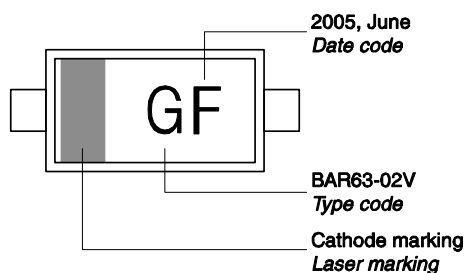
Package Outline



Foot Print

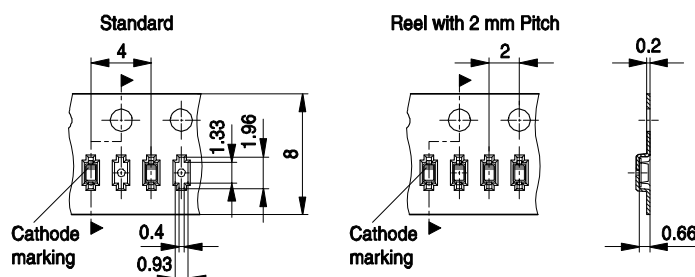


Marking Layout (Example)

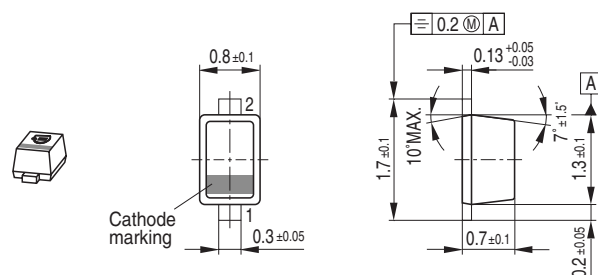


Standard Packing

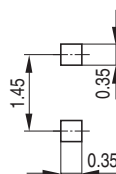
Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 180$ mm = 8.000 Pieces/Reel (2 mm Pitch)
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



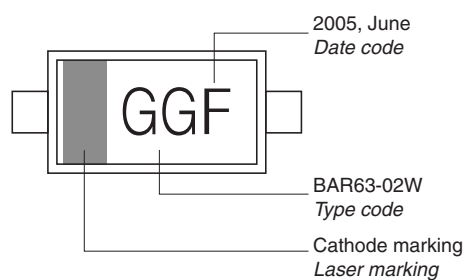
Package Outline



Foot Print

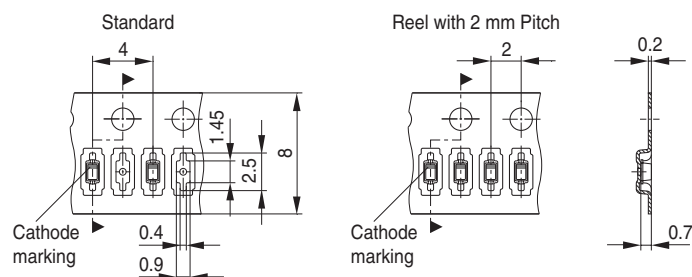


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)
 Reel ø330 mm = 10.000 Pieces/Reel



Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

1) New Marking Layout for SC75, implemented at October 2005.

Technical drawing of the 025M-A photoresistor, showing isometric, top, and side views with dimensions in millimeters.

Isometric View: Shows the physical component with a 'G' marking on the top surface.

Top View:

- Overall width: $1.25^{+0.2}_{-0.1}$
- Overall height: 2.5 ± 0.2
- Internal width (excluding leads): 2
- Internal height (excluding leads): 1
- Distance from bottom edge to internal width line: $0.3^{+0.1}_{-0.05}$
- Feature: Cathode marking (indicated by a shaded area and a dashed line).
- Part Number: $\equiv 0.25 \text{ (M) A}$

Side View:

- Top lead width: $0.9^{+0.2}_{-0.1}$
- Top lead thickness: 0 ± 0.05
- Mounting hole diameter: 0.45 ± 0.15
- Mounting hole offset from bottom edge: $1.7^{+0.2}_{-0.1}$
- Mounting hole offset from side edge: $0.3^{+0.05}_{-0.2}$
- Bottom lead width: $0.15^{+0.1}_{-0.06}$

BAR63-03W
Type code

Cathode marking
Color ink or laser marking

Technical drawing of a cathode marking. The drawing shows a side view and a cross-section. The side view has a total width of 4, a central hole with a diameter of 2, and a distance of 2.9 from the center to the right edge. The cross-section shows a total width of 0.65 and a distance of 1.35 from the center to the right edge. The text "Cathode marking" is written below the side view.

Edition 2009-11-16

**Published by
Infineon Technologies AG
81726 Munich, Germany**

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